

Serial No. 09/450,632  
Docket No. 550718-070  
Second Preliminary Amendment

9. A lead-free solder alloy according to claim 3 wherein Ni is added to a ~~solved~~ base alloy of Sn-Cu.

10. A lead-free solder alloy according to claim 1 wherein Cu is added to a ~~solved~~ base alloy of Sn-Ni.

11. A lead-free solder alloy according to claim 2 wherein Cu is added to a ~~solved~~ base alloy of Sn-Ni.

12. A lead-free solder alloy according to claim 3 wherein Cu is added to a ~~solved~~ base alloy of Sn-Ni.

13. A lead-free solder alloy according to claim 1 wherein 0.001-1 wt% Ge is further added.

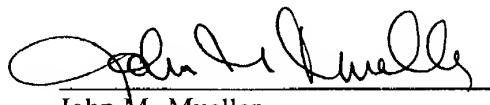
14. A lead-free solder alloy according to claim 2 wherein 0.001-1 wt% Ge is further added.

15. A lead-free solder alloy according to claim 3 wherein 0.001-1 wt% Ge is further added.--

Remarks

The above amendments have been made in order to remove multiple dependent claims.

Respectfully submitted,

  
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